**XL-0201UWC** **Technical Data**

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## 电性参数

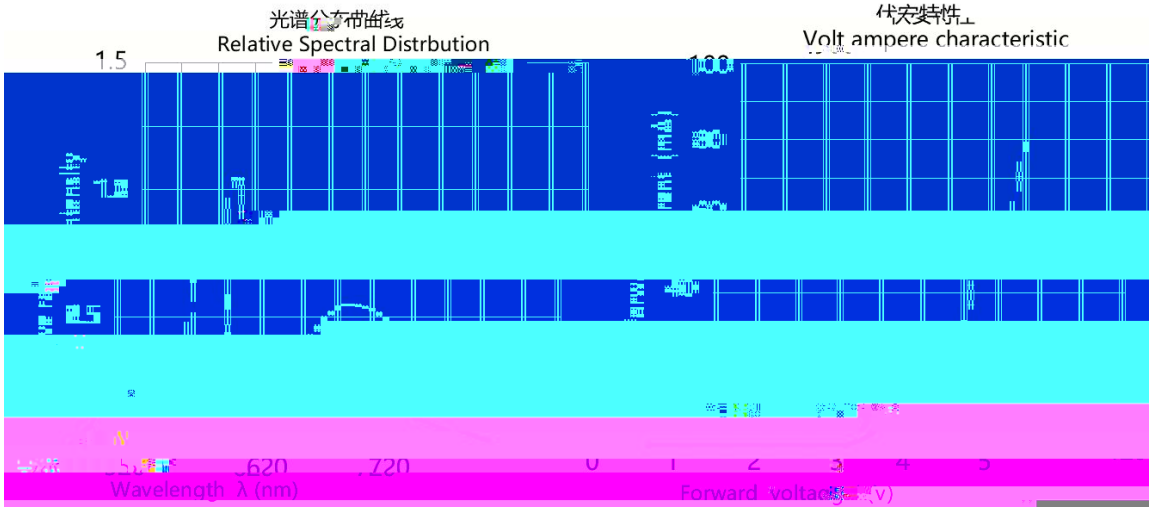
**Electrical Characteristics**

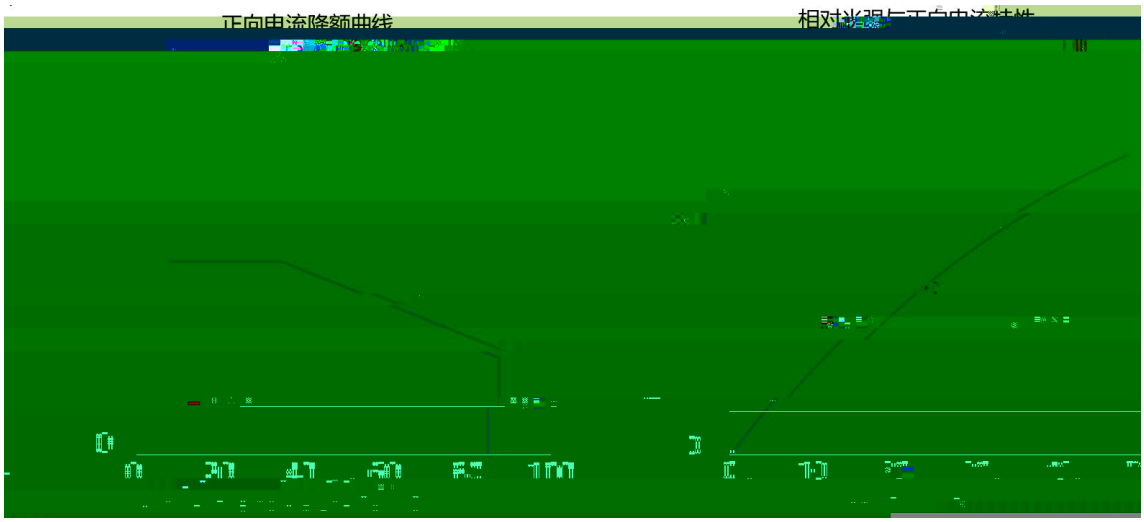
✧

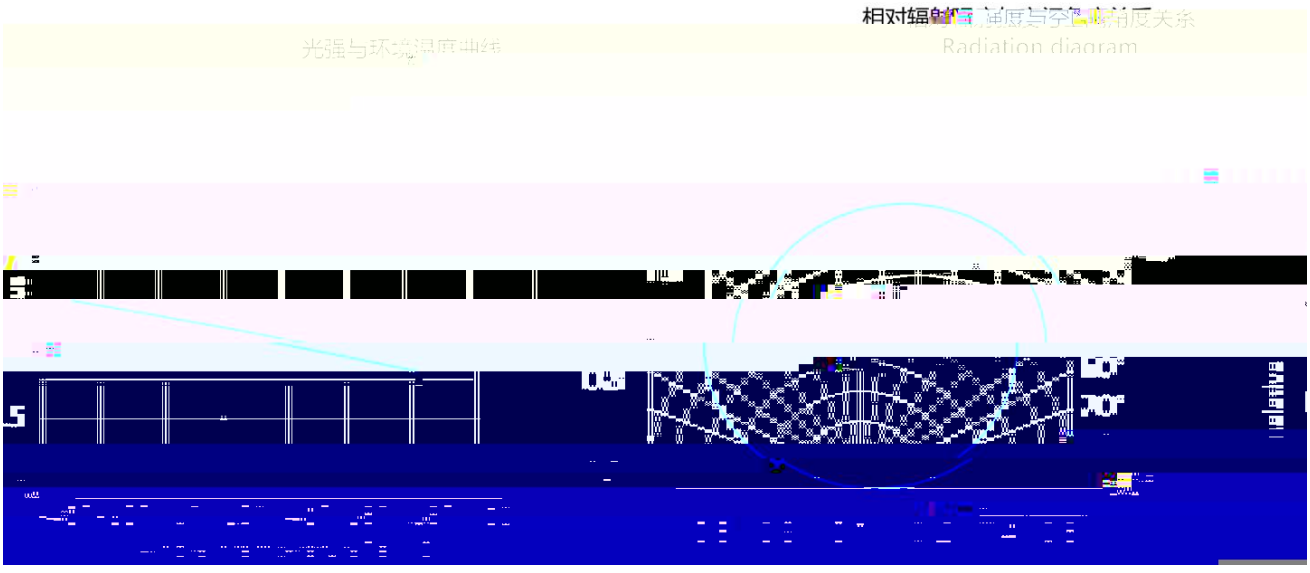
| Bin Code | CIE-X | CIE-Y | Bin Code | CIE-X | CIE-Y | Bin Code | CIE-X | CIE-Y | Bin Code | CIE-X | CIE-Y | Bin Code | CIE-X | CIE-Y |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | 0.3099 | 0.3509 | | 0.3202 | 0.3532 | | 0.3290 | 0.3690 | | 0.3381 | 0.3762 | | 0.3005 | 0.3415 |
| | 0.3107 | 0.3450 | | 0.3290 | 0.3614 | | 0.3290 | 0.3614 | | 0.3379 | 0.3689 | | 0.3017 | 0.3360 |
| F5 | 0.3201 | 0.3542 | G5 | 0.3290 | 0.3690 | H5 | 0.3379 | 0.3689 | I5 | 0.3472 | 0.3764 | E5 | 0.3107 | 0.3450 |
| | 0.3196 | 0.3602 | | 0.3196 | 0.3602 | | 0.3381 | 0.3762 | | 0.3480 | 0.3840 | | 0.3099 | 0.3509 |
| | 0.3107 | 0.3450 | | | | | | | | | | | | |
| F6 | | | G6 | | | | | | | | | | | |

## 典型特性曲线

## Typical Characteristics Curves





ч 25Ñ5Ņ/Note' If not otherwise indicated the test environment temp erature is 25Ñ5Ņ

**Reliability experiment**

| Class | Test item | Testing environment | Testing time | Reference standard |
|---|---|---|---|---|
| Endurance test | Working life | Continuous lighting at the maximum rated current at room temperature:Test it at 20mA. | 1000 hours | MIL-STD-750D:1026<br>MIL-STD-883D:1005<br>JIS C 7021:B-1 |
| | High temperature and high humidity storage | IR-Reflow In-Board, 2 Times<br>Ta= 85±5℃, RH= 90~95% | 240hours<br>(240hours) | MIL-STD-202F:103B<br>JIS C 7021:B-11 |
| | High-temperature storage | Ta= 85±5℃ | 1000 hours<br>-24℃ +72℃ )<br>-24hours+72hours | MIL-STD-883D:1008<br>JIS C 7021:B-10 |
| | Low temperature storage | Ta= -40±5℃ | | JIS C 7021:B-12 |
| Environmental testing | Cold and hot cycle | 105℃ 25℃ -55℃ 25℃<br>30mins 5mins 30mins 5mins | 100<br>100 Circles | MIL-STD-202F:107D<br>MIL-STD-750D:1051<br>MIL-STD-883D:1010 |
| | Hot and cold impact | IR-Reflow In-Board, 2 Times' 100±5℃<br>-40℃±5℃' 20mins' 20mins | 100<br>100 Circles | MIL-STD-202F:107D<br>MIL-STD-750D:1051<br>MIL-STD-883D:1011 |
| | Anti-tin test | T.sol= 260±5℃ | 10±1secs<br>2 2times | MIL-STD-202F:210A<br>MIL-STD-750D:2031<br>JIS C 7021:A-1 |
| | Infrared reflowwelding There is lead process | heat up speed(183℃ ) 3℃/ keep temperature 125(±25)℃ 120 keep temperature183℃ 60-150 maximum temperature 235℃+5/-0℃ keep235℃+5/-0℃ 10-15 cooling rate 6℃/ | -------- | MIL-STD-750D:2031.2<br>J-STD-020C |
| | Infrared reflow welding Lead-free process | heat up speed(217℃ ) 3℃/ keep temperature 175(±25)℃ 180 keep temperature217℃ 60-120 maximum temperature 255℃+0/-5℃ keep255℃+0/-5℃ 5-10 cooling rate 6℃/ | -------- | MIL-STD-750D:2031.2<br>J-STD-020C |
| | Weldability test | Soldering temperature T.sol= 235±5℃ Immersion speed 25±2.5 mm/ 95% Tin loading rate 95% pad area Immersion time: 2±0.5 seconds | Immersion time 2±0.5 | MIL-STD-202F:208D<br>MIL-STD-750D:2026<br>MIL-STD-883D:2003<br>IEC 68 Part 2-20<br>JIS C 7021:A-2 |

外形尺寸:

**Outline Dimension**

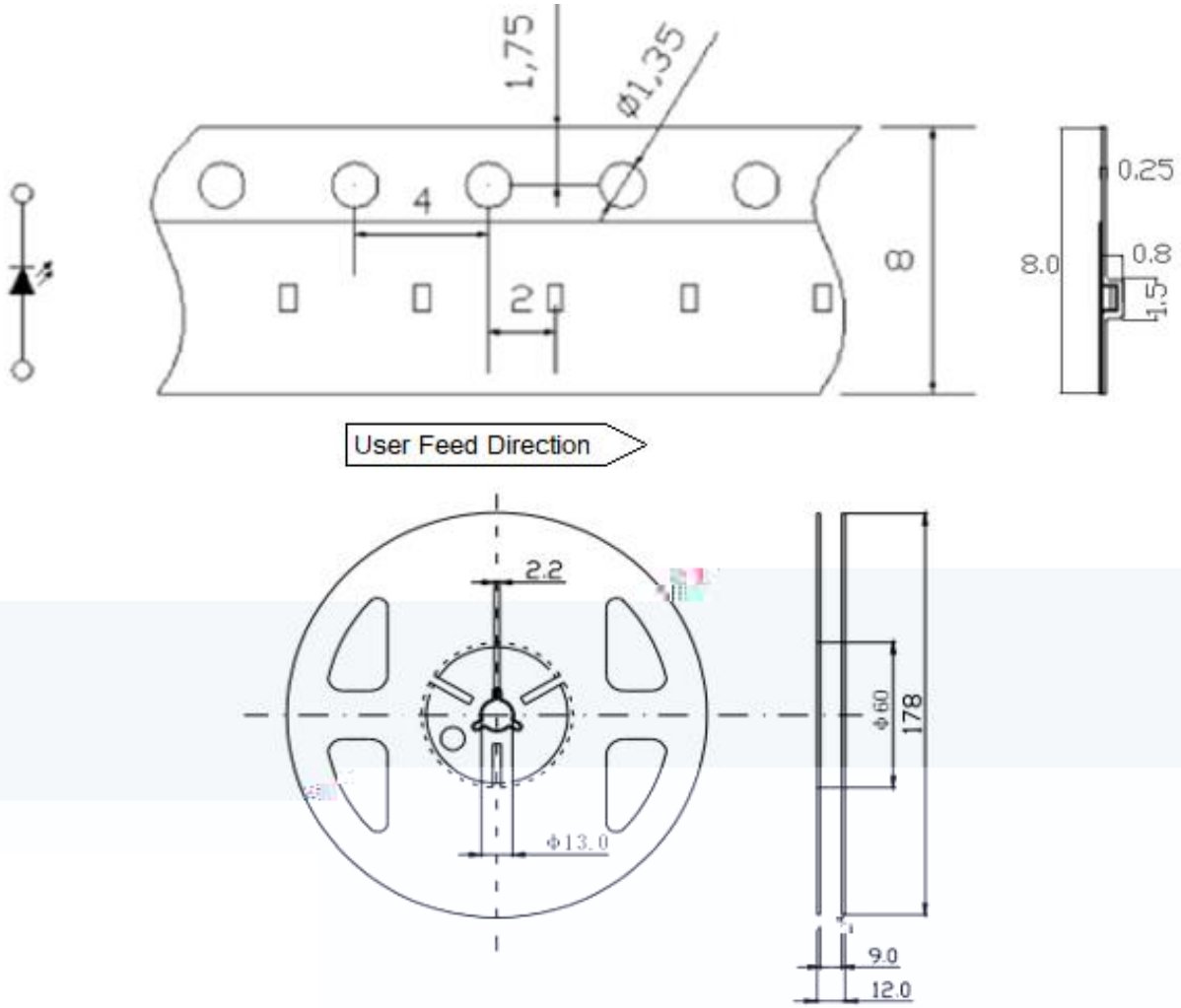
' 1.ㄚβ' ^ mm~
Remarks: 1 Unit: mm

2.`E ' ≠ ↕ ㄐÑ0.10mm
2. Tolerance: Ñ 0.10mm unless otherwise spec`i · þ

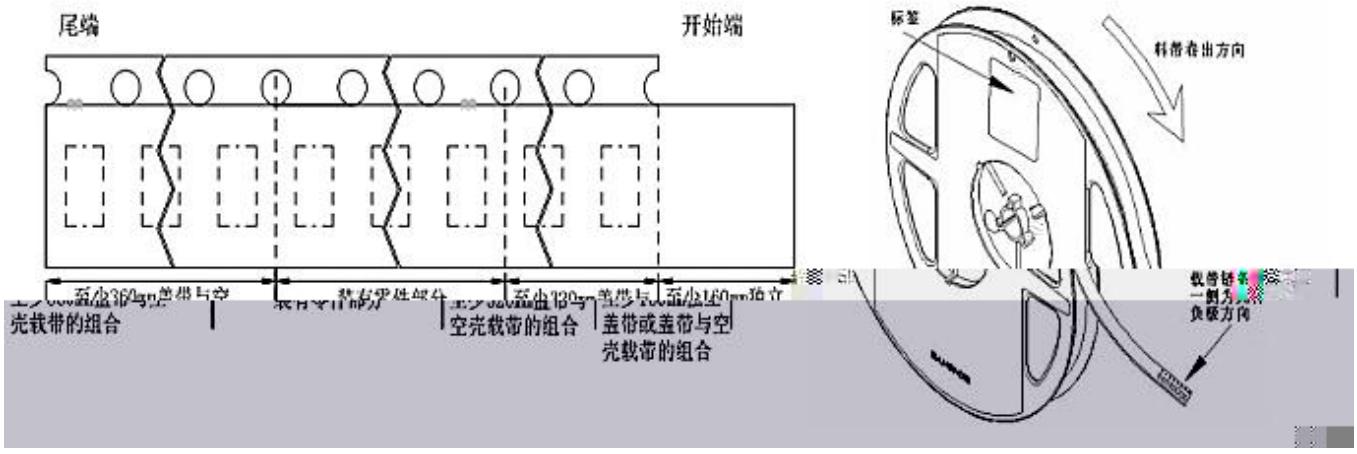
# 包装（1）

**Packaging (1)**

**载带与圆盘尺寸 Belt and disk dimensions**



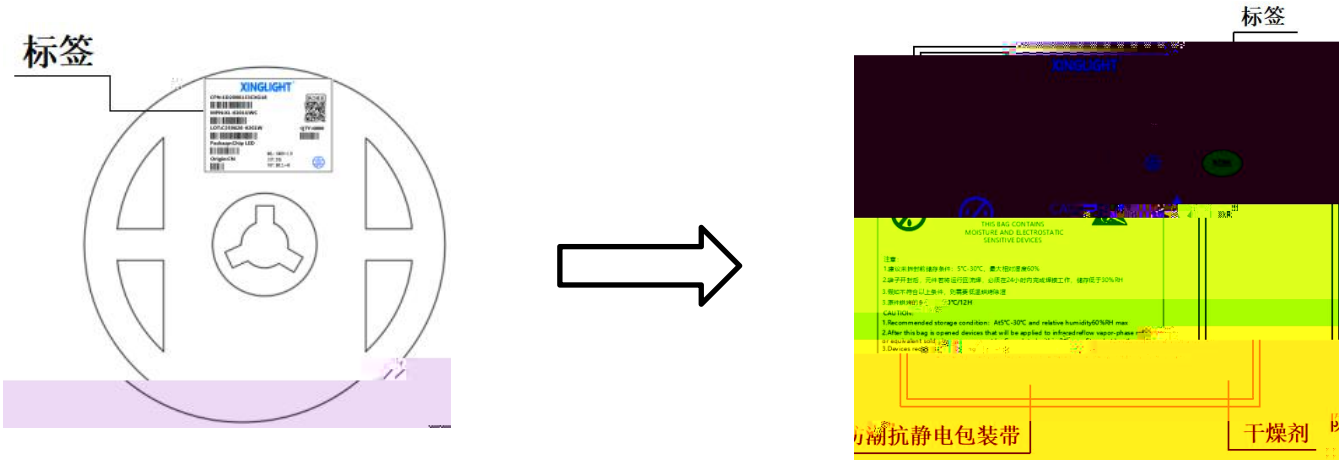

**圆盘及载带卷出方向及空穴规格 Disk and carrier belt direction of roll and hole dimensions**



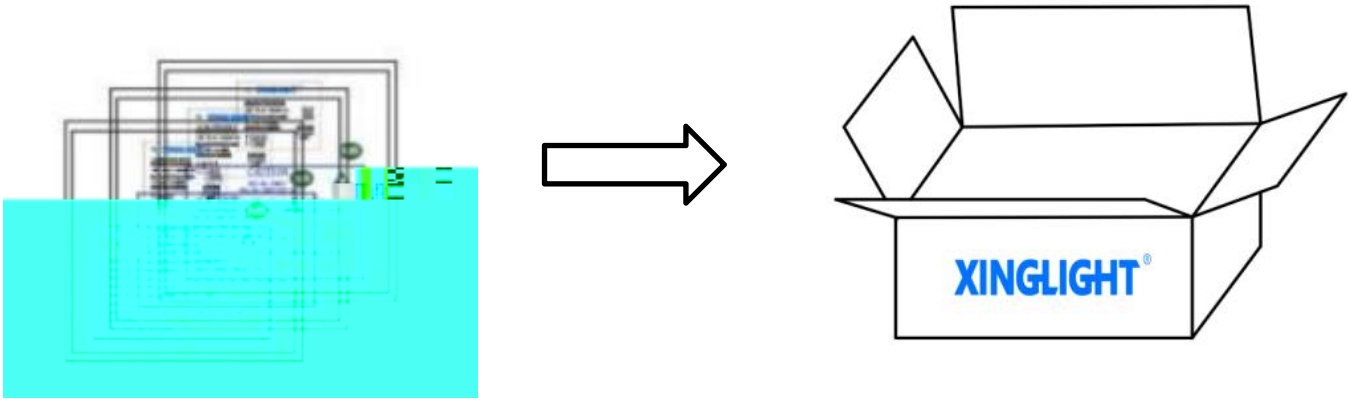
# 装（2）

**ging (2)**

Mc ure Proo d Antti-Electrostic Foil Bag




Ù Cardboard Box




Ù Label Expantion

# 焊接指导（1）

## Guideline for Soldering (1)

### 1. 使用烙铁人手焊接

**Hand Soldering**

ز ضي ḱ ڊ ' Ӈ ą ' ą w ٧ G 30W ˘ Ḡ
ضي 300Ņ ץ Ӈ˘ ғ ɷ ز ₩ ˘ Ь 3 Â
Ţ Ь ƀ LED ڃ ڜ˘ Â

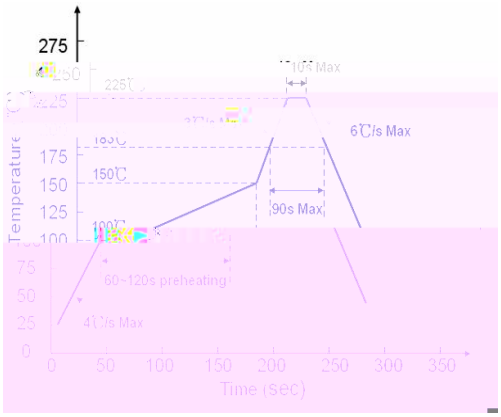
Manual welding is recommended only for repair and heavy industry situations. A soldering iron of less than 30W is recommended to be used in Hand Soldering. Please keep the temperature of the soldering iron under 300Ņ while soldering. Each terminal of the LED is to go for less than 3 second and for one time only.

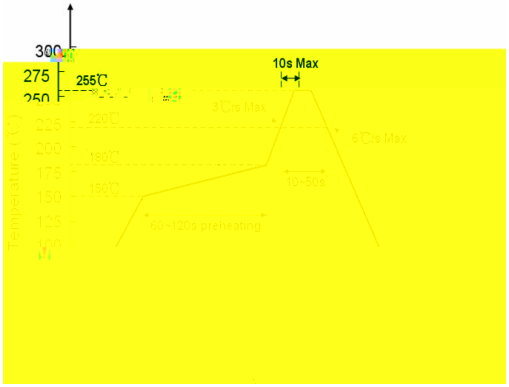
Be careful because the damage of the product is often started at the time of the hand soldering.

### 2. 回流焊接：

ą ץ Ӈ ڠ ڍ Â

**Reflow Soldering:** Use the conditions shown in the under Figure ofPb-Free Reflow Soldering.




└ Lead process

└ lead free

ڠ ز Ң Â

Reflow soldering should not be done more than two times.

ضي ڠ ʼn Ţ˘ Ь LED ٧ к ٧ ٨ ʐ Â

Stress on the LEDs should be avoided during heating in soldering process.

ضي U˘ ڃ Ӈ ⌠ Ң U˘ ʼP ỉ ɾ Â

After soldering, do not deal with the product before its temperature drop down to room temperature.

ڃ g ␣ └ضي240 ¤ 5Ņ/6S

The recommended maximum welding temperature for the product is 240 ¤ 5 /6s

**Cleaning**

ضِ U ą ˘ ضِ Ь ɢ 30Ņ ɒ Йį 3 № ˘ Ь ɢ 50Ņ ɒ Йį 30

Â ą ì ɾ ³ ╕ ╠˘ ѽ ą ╕ Ь Ψ LED ė № ᴴ Â

Ƶ ˘ ₩ ѡ Ь 300W˘ Ղ ↕ˆ LED Ɛ₁₇ĎiᵾᴴÂ ĺ ᵣ

’ ѽ ɒ Ղ Ψ LED ᴴ Â

## 1)

## Precautions (1)

1. **贮存：**

**Storage**

¥ ˚˚ ج ą ˊ ˇ ╕ˇ ˚˚ ج ₩ Ḡ Â

Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to a minimum.

¥ ╠ˇ ˚˚ ج ض Ь G 30Ņˇ Ь G 40%RH

**Design Consideration**

ˇ LED Ь ν ˇ ą Ḡ ˇ ϩ ↕ˇ ≀ ΐ .

Ψ ΐ. ˇ ˆ ˚ ڃ Â

ą ɣ Ѝ A˜ ˇ ѫ LED ’ Ь ą ˆ B˜ ˇ ضِ

≀ ¯ Ѝ LED ≀ˆ